



Material Content Data Sheet



Sales Product Name		IPD110N12N3 G		Issued		25. January 2018		
MA#		MA001662912						
Package		PG-TO252-3-313		Weight*		321.06 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.755	1.79	1.79	17925	17925
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		459	
	non noble metal	copper	7440-50-8	147.096	45.82	45.88	458159	458756
	non noble metal	aluminium	7429-90-5	3.792	1.18	1.18	11811	11811
wire	non noble metal	aluminium	7429-90-5	3.792	1.18	1.18	11811	11811
encapsulation	organic material	carbon black	1333-86-4	1.352	0.42		4211	
	plastics	epoxy resin	-	23.659	7.37		73691	
	inorganic material	silicondioxide	60676-86-0	110.184	34.32	42.11	343191	421093
leadfinish	non noble metal	tin	7440-31-5	3.740	1.16	1.16	11649	11649
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4424	4435
solder	non noble metal	tin	7440-31-5	0.093	0.03		290	
	noble metal	silver	7440-22-4	0.117	0.04		363	
	non noble metal	lead	7439-92-1	4.452	1.39	1.46	13868	14521
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	5.97	5.98	59732	59810
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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